

APR 24 2003

SHEET 1 OF 1

Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY DOCKET NO.

198092US-2S DIV

SERIAL NO.

09/684,904

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

HIRONOBU KON, ET AL.

RCE FILED

DECEMBER 19, 2002

GROUP

2814

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES	NO
DF	AP	JP- 08-162631	06/21/96	Japan		x
DR	AQ	JP 10-229671	08/25/98	Japan		x
	AR					
	AS					
	AT					
	AU					
	AV					
	AW					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AX	
	AY	
	AZ	
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Examiner

Qu Shi

Date Considered

5/26/05

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

10/10/00

SHEET 1 OF 2

Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY DOCKET NO.
198092US-2S DIVSERIAL NO.
New Divisional Application

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Hironobu KON et al

FILING DATE

Herewith

GROUP

2814

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
TT	AA	5,729,032	03/1998	TOMOMATSU ET AL			
TT	AB	5,610,439	03/11/97	HIYOSHI ET AL			
TT	AC	5,530,277	06/1996	OTSUKI ET AL			
TT	AD	5,448,083	09/05/95	KITAGAWA ET AL			
TT	AE	5,329,142	07/12/94	KITAGAWA ET AL			
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		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
DF	AO	44 29733 A1	3/1995	GERMANY (with abstract)		X
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TT	AW	Hideo Matsuda, "Pressure Contact Assembly Technology of High Power Devices," Power Semiconductor Devices and ICs. 1997. ISPSD '97 1997 IEEE International Symposium on, May 1997, pp. 17-24.
TT	AX	M. Kudoh, et al., "Current Sensing IGBT for Future Intelligent Power Module," Power Semiconductor Devices and ICs. 1996. ISPSD '96 Proceedings., 8th International Symposium on, May 1996, pp. 303-306.
TT	AY	Mitsuhiko Kitagawa, et al., "A 4500V Injection Enhanced Insulated Gate Bipolar Transistor (IEGT) Operating in a Mode Similar to a Thyristor," IEDM, December 1993, pp. 679-682.
TT	AZ	Noriyuki Iwamuro, "A New Vertical IGBT Structure with a Monolithic Over-Current, Over-Voltage, and Over-Temperature Sensing and Protecting Circuit," IEEE Electron Device Lett., Vol. 16, No. 9, September 1995, pp. 399-401.

Examiner

Date Considered 10/02/01

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Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 198092US-2S DIV		SERIAL NO. New Divisional Application	
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				FILING DATE Herewith		GROUP 2814	
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
77	AAC	Yasukazu Seki, et al., "A New IGBT with a Monolithic Over-Current Protection Circuit," Proc. of the 6 th Internat. Symposium on Power Semiconductor Davos, Switzerland, May 31-June 2, 1994, pp. 31-35.					
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